



S/N 09/858,238

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Tee Onn Chong et al.

Examiner: John B. Vigushin

Serial No.: 09/858,238

Group Art Unit: 2827

Filed: May 15, 2001

Docket No.: 884.419US1

Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS

Assignee: Intel Corporation

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Applicants have reviewed the Office Action mailed on January 28, 2003. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from April 28, 2003 to May 28, 2003.

The amendments are made in the "revised amendment format" announced by the Deputy Commissioner for Patent Examination Policy on January 31, 2003.

06/02/2003 GWORDDF1 00000005 190743 09858238

02 FC:1201 18.00 CH 150.00 OP
~~03 FC:1202 18.00 CH~~

Adjustment date: 06/03/2003 JADB01
06/02/2003 GWORDDF1 00000005 190743 09858238
03 FC:1202 18.00 CR